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Understanding Embedded - FPGAs (Field Programmable Gate Array)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

Product Status	Obsolete
Number of LABs/CLBs	416
Number of Logic Elements/Cells	4160
Total RAM Bits	53248
Number of I/O	252
Number of Gates	263000
Voltage - Supply	2.375V ~ 2.625V
Mounting Type	Surface Mount
Operating Temperature	0°C ~ 85°C (TJ)
Package / Case	356-LBGA
Supplier Device Package	356-BGA (35x35)
Purchase URL	https://www.e-xfl.com/product-detail/intel/ep20k100cb356c9

...and More Features

- Low-power operation design
 - 1.8-V supply voltage (see Table 2)
 - Copper interconnect reduces power consumption
 - MultiVolt™ I/O support for 1.8-V, 2.5-V, and 3.3-V interfaces
 - ESBs offering programmable power-saving mode
- Flexible clock management circuitry with up to four phase-locked loops (PLLs)
 - Built-in low-skew clock tree
 - Up to eight global clock signals
 - ClockLock™ feature reducing clock delay and skew
 - ClockBoost™ feature providing clock multiplication and division
 - ClockShift™ feature providing programmable clock phase and delay shifting
- Powerful I/O features
 - Compliant with peripheral component interconnect Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2* for 3.3-V operation at 33 or 66 MHz and 32 or 64 bits
 - Support for high-speed external memories, including DDR synchronous dynamic RAM (SDRAM) and ZBT static RAM (SRAM)
 - 16 input and 16 output LVDS channels
 - Direct connection from I/O pins to local interconnect providing fast t_{CO} and t_{SU} times for complex logic
 - MultiVolt I/O support for 1.8-V, 2.5-V, and 3.3-V interfaces
 - Programmable clamp to V_{CCIO}
 - Individual tri-state output enable control for each pin
 - Programmable output slew-rate control to reduce switching noise
 - Support for advanced I/O standards, including low-voltage differential signaling (LVDS), LVPECL, PCI-X, AGP, CTT, SSTL-3 and SSTL-2, GTL+, and HSTL Class I
 - Supports hot-socketing operation
 - Pull-up on I/O pins before and during configuration

Table 2. APEX 20KC Supply Voltages

Feature	Voltage
Internal supply voltage (V_{CCINT})	1.8 V
MultiVolt I/O interface voltage levels (V_{CCIO})	1.8 V, 2.5 V, 3.3 V, 5.0 V (1)

Note:

- (1) APEX 20KC devices can be 5.0-V tolerant by using an external resistor.

Table 4. APEX 20KC FineLine BGA Package Options & I/O Count *Notes (1), (2)*

Device	144 Pin	324 Pin	484 Pin	672 Pin	1,020 Pin
EP20K100C	93	246			
EP20K200C			376	376	
EP20K400C				488 (3)	
EP20K600C				508 (3)	588
EP20K1000C				508 (3)	708
EP20K1500C					808

Notes to tables:

- (1) I/O counts include dedicated input and clock pins.
- (2) APEX 20KC device package types include thin quad flat pack (TQFP), plastic quad flat pack (PQFP), power quad flat pack (RQFP), 1.27-mm pitch ball-grid array (BGA), and 1.00-mm pitch FineLine BGA packages.
- (3) This device uses a thermally enhanced package, which is taller than the regular package. Consult the *Altera Device Package Information Data Sheet* for detailed package size information.

Table 5. APEX 20KC QFP & BGA Package Sizes

Feature	144-Pin TQFP	208-Pin PQFP	240-Pin PQFP	356-Pin BGA	652-Pin BGA
Pitch (mm)	0.50	0.50	0.50	1.27	1.27
Area (mm ²)	484	924	1,218	1,225	2,025
Length × Width (mm × mm)	22.0 × 22.0	30.4 × 30.4	34.9 × 34.9	35.0 × 35.0	45.0 × 45.0

Table 6. APEX 20KC FineLine BGA Package Sizes

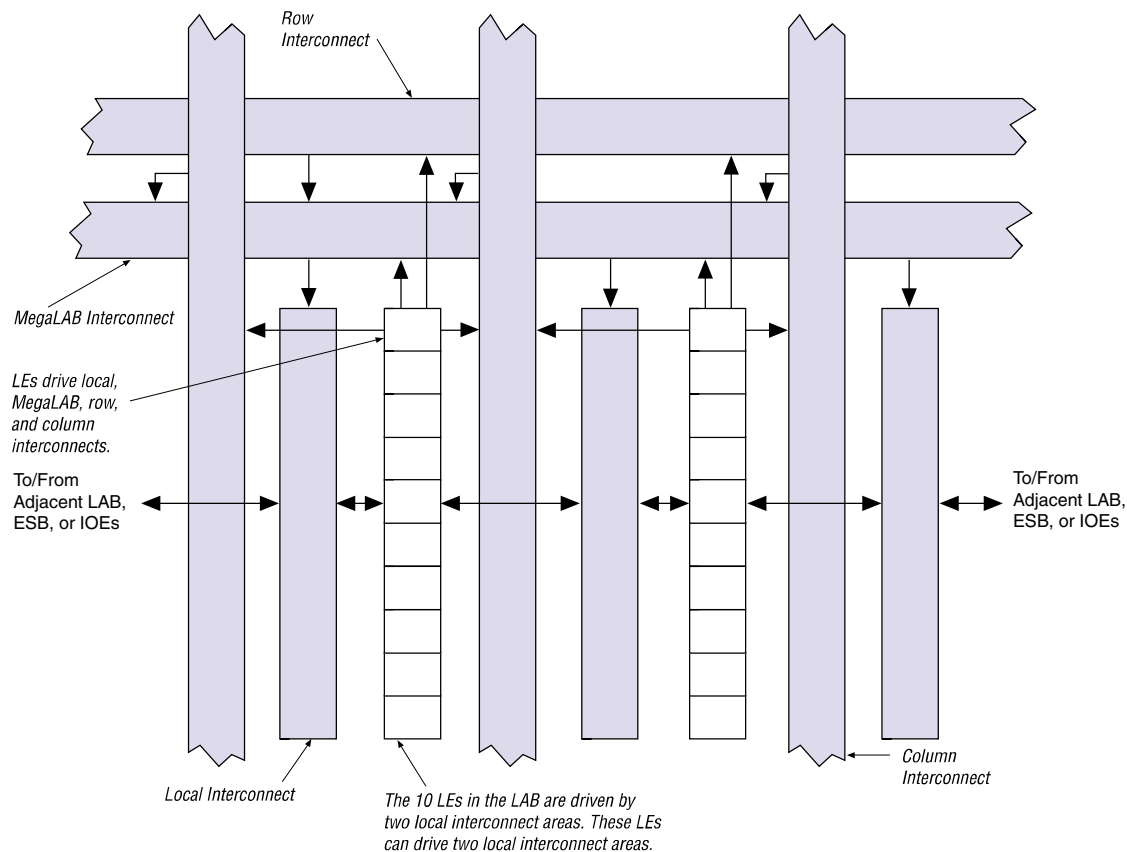
Feature	144 Pin	324 Pin	484 Pin	672 Pin	1,020 Pin
Pitch (mm)	1.00	1.00	1.00	1.00	1.00
Area (mm ²)	169	361	529	729	1,089
Length × Width (mm × mm)	13 × 13	19 × 19	23 × 23	27 × 27	33 × 33

Table 7. APEX 20KC Device Features (Part 2 of 2)

Feature	APEX 20KC Devices
I/O standard support	1.8-V, 2.5-V, 3.3-V, 5.0-V I/O 3.3-V PCI and PCI-X 3.3-V AGP CTT GTL+ LVC MOS LV TTL True-LVDS™ and LVPECL data pins (in EP20K400C and larger devices) LVDS and LVPECL clock pins (in all devices) LVDS and LVPECL data pins up to 156 Mbps (in all devices) HSTL Class I PCI-X SSTL-2 Class I and II SSTL-3 Class I and II
Memory support	CAM Dual-port RAM FIFO RAM ROM

All APEX 20KC devices are reconfigurable and are 100% tested prior to shipment. As a result, test vectors do not have to be generated for fault-coverage purposes. Instead, the designer can focus on simulation and design verification. In addition, the designer does not need to manage inventories of different application-specific integrated circuit (ASIC) designs; APEX 20KC devices can be configured on the board for the specific functionality required.

APEX 20KC devices are configured at system power-up with data stored in an Altera serial configuration device or provided by a system controller. Altera offers in-system programmability (ISP)-capable EPC16, EPC2, and EPC1 configuration devices, which configure APEX 20KC devices via a serial data stream. Moreover, APEX 20KC devices contain an optimized interface that permits microprocessors to configure APEX 20KC devices serially or in parallel, and synchronously or asynchronously. The interface also enables microprocessors to treat APEX 20KC devices as memory and configure the device by writing to a virtual memory location, making reconfiguration easy.

Figure 3. LAB Structure

Each LAB contains dedicated logic for driving control signals to its LEs and ESBs. The control signals include clock, clock enable, asynchronous clear, asynchronous preset, asynchronous load, synchronous clear, and synchronous load signals. A maximum of six control signals can be used at a time. Although synchronous load and clear signals are generally used when implementing counters, they can also be used with other functions.

Each LAB can use two clocks and two clock enable signals. Each LAB's clock and clock enable signals are linked (e.g., any LE in a particular LAB using CLK1 will also use CLKEN1). LEs with the same clock but different clock enable signals either use both clock signals in one LAB or are placed into separate LABs.

If both the rising and falling edges of a clock are used in a LAB, both LAB-wide clock signals are used.

Normal Mode

The normal mode is suitable for general logic applications, combinatorial functions, or wide decoding functions that can take advantage of a cascade chain. In normal mode, four data inputs from the LAB local interconnect and the carry-in are inputs to a four-input LUT. The Quartus II Compiler automatically selects the carry-in or the `DATA3` signal as one of the inputs to the LUT. The LUT output can be combined with the cascade-in signal to form a cascade chain through the cascade-out signal. LEs in normal mode support packed registers.

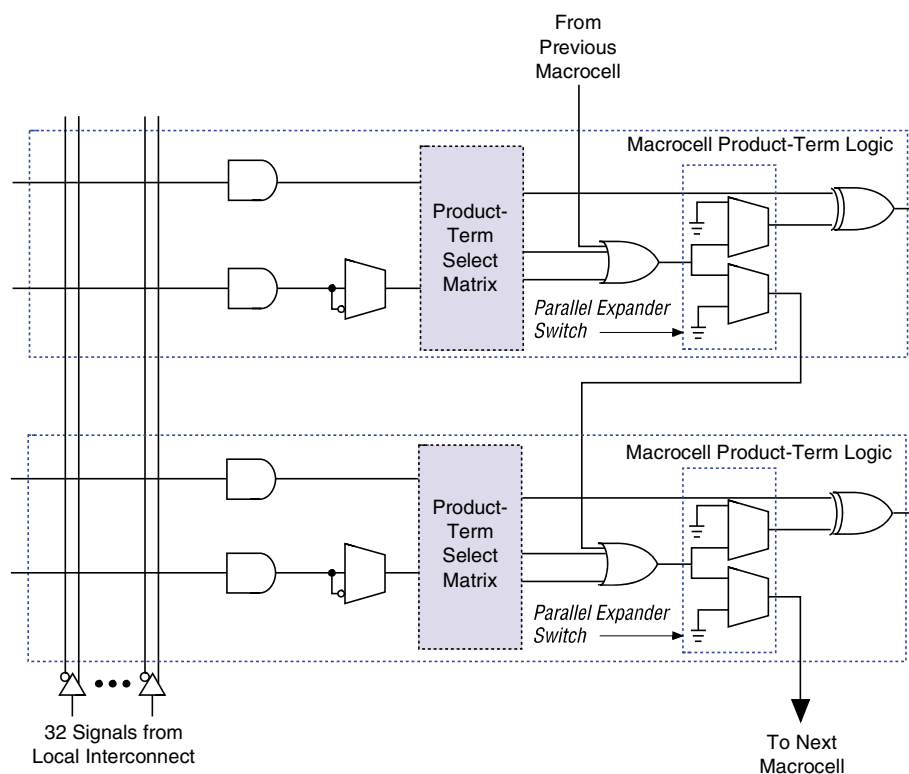
Arithmetic Mode

The arithmetic mode is ideal for implementing adders, accumulators, and comparators. An LE in arithmetic mode uses two 3-input LUTs. One LUT computes a three-input function; the other generates a carry output. As shown in [Figure 8](#), the first LUT uses the carry-in signal and two data inputs from the LAB local interconnect to generate a combinatorial or registered output. For example, when implementing an adder, this output is the sum of three signals: `DATA1`, `DATA2`, and carry-in. The second LUT uses the same three signals to generate a carry-out signal, thereby creating a carry chain. The arithmetic mode also supports simultaneous use of the cascade chain. LEs in arithmetic mode can drive out registered and unregistered versions of the LUT output.

The Quartus II software implements parameterized functions that use the arithmetic mode automatically where appropriate; the designer does not need to specify how the carry chain will be used.

Counter Mode

The counter mode offers clock enable, counter enable, synchronous up/down control, synchronous clear, and synchronous load options. The counter enable and synchronous up/down control signals are generated from the data inputs of the LAB local interconnect. The synchronous clear and synchronous load options are LAB-wide signals that affect all registers in the LAB. Consequently, if any of the LEs in an LAB use the counter mode, other LEs in that LAB must be used as part of the same counter or be used for a combinatorial function. The Quartus II software automatically places any registers that are not used by the counter into other LABs.

Figure 16. APEX 20KC Parallel Expanders

Embedded System Block

The ESB can implement various types of memory blocks, including dual-port RAM, ROM, FIFO, and CAM blocks. The ESB includes input and output registers; the input registers synchronize writes, and the output registers can pipeline designs to improve system performance. The ESB offers a dual-port mode, which supports simultaneous reads and writes at two different clock frequencies. Figure 17 shows the ESB block diagram.

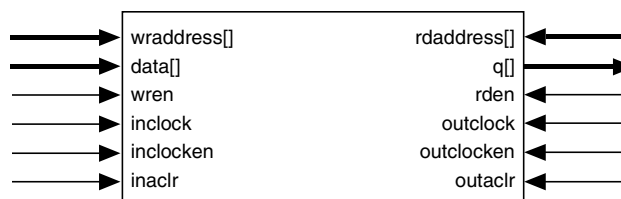
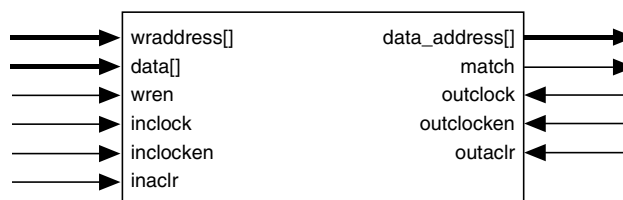
Figure 17. ESB Block Diagram

Figure 23. APEX 20KC CAM Block Diagram

CAM can be used in any application requiring high-speed searches, such as networking, communications, data compression, and cache management.

The APEX 20KC on-chip CAM provides faster system performance than traditional discrete CAM. Integrating CAM and logic into the APEX 20KC device eliminates off-chip and on-chip delays, improving system performance.

When in CAM mode, the ESB implements 32-word, 32-bit CAM. Wider or deeper CAM can be implemented by combining multiple CAMs with some ancillary logic implemented in LEs. The Quartus II software combines ESBs and LEs automatically to create larger CAMs.

CAM supports writing “don’t care” bits into words of the memory. The “don’t care” bit can be used as a mask for CAM comparisons; any bit set to “don’t care” has no effect on matches.

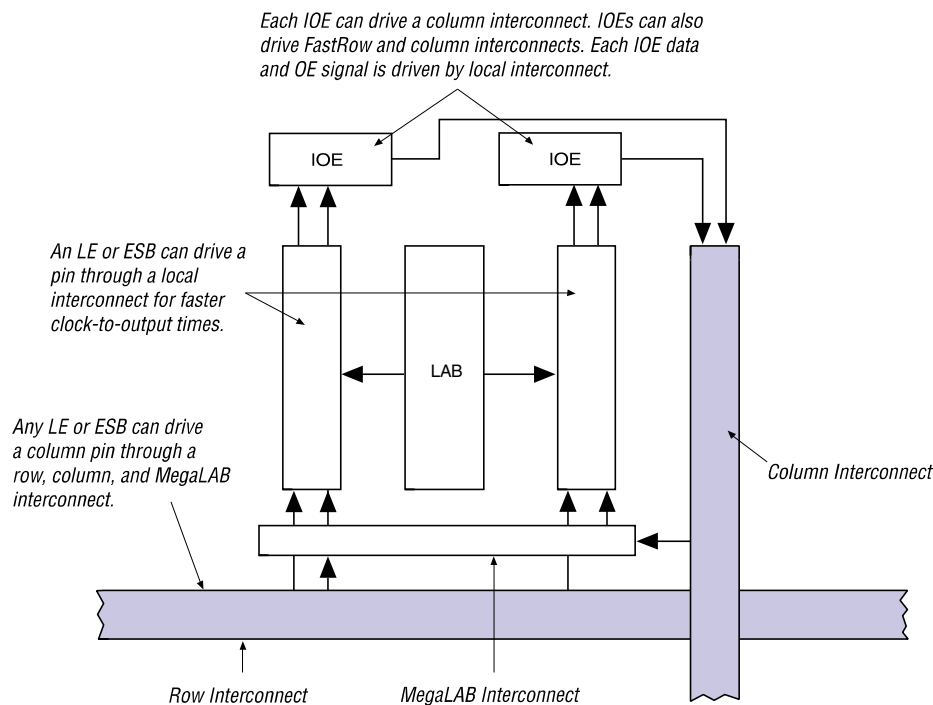
The output of the CAM can be encoded or unencoded. When encoded, the ESB outputs an encoded address of the data’s location. For instance, if the data is located in address 12, the ESB output is 12. When unencoded, the ESB uses its 16 outputs to show the location of the data over two clock cycles. In this case, if the data is located in address 12, the 12th output line goes high. When using unencoded outputs, two clock cycles are required to read the output because a 16-bit output bus is used to show the status of 32 words.

The encoded output is better suited for designs that ensure duplicate data is not written into the CAM. If duplicate data is written into two locations, the CAM’s output will be incorrect. If the CAM may contain duplicate data, the unencoded output is a better solution; CAM with unencoded outputs can distinguish multiple data locations.

CAM can be pre-loaded with data during configuration, or it can be written during system operation. In most cases, two clock cycles are required to write each word into CAM. When “don’t care” bits are used, a third clock cycle is required.

Figure 27 shows how a column IOE connects to the interconnect.

Figure 27. Column IOE Connection to the Interconnect



Dedicated Fast I/O Pins

APEX 20KC devices incorporate an enhancement to support bidirectional pins with high internal fan-out such as PCI control signals. These pins are called dedicated fast I/O pins (**FAST1**, **FAST2**, **FAST3**, and **FAST4**) and replace dedicated inputs. These pins can be used for fast clock, clear, or high fan-out logic signal distribution. They also can drive out. The dedicated fast I/O pin data output and tri-state control are driven by local interconnect from the adjacent MegaLAB for high speed.

Advanced I/O Standard Support

APEX 20KC IOEs support the following I/O standards: LVTTTL, LVCMOS, 1.8-V I/O, 2.5-V I/O, 3.3-V PCI, PCI-X, 3.3-V AGP, LVDS, LVPECL, GTL+, CTT, HSTL Class I, SSTL-3 Class I and II, and SSTL-2 Class I and II.



For more information on I/O standards supported by APEX 20KC devices, see *Application Note 117 (Using Selectable I/O Standards in Altera Devices)*.

The APEX 20KC device contains eight I/O banks. In QFP packages, the banks are linked to form four I/O banks. The I/O banks directly support all standards except LVDS and LVPECL. All I/O banks can support LVDS and LVPECL with the addition of external resistors. In addition, one block within a bank contains circuitry to support high-speed True-LVDS and LVPECL inputs, and another block within a bank supports high-speed True-LVDS and LVPECL outputs. The LVDS blocks support all of the I/O standards. Each I/O bank has its own VCCIO pins. A single device can support 1.8-V, 2.5-V, and 3.3-V interfaces; each bank can support a different standard independently. Each bank can also use a separate V_{REF} level so that each bank can support any of the terminated standards (such as SSTL-3) independently. Within a bank, any one of the terminated standards can be supported. EP20K400C and larger APEX 20KC devices support the LVDS interface for data pins (smaller devices support LVDS clock pins, but not data pins). All EP20K400C and larger devices support the LVDS interface for data pins up to 155 Mbit per channel; EP20K400C devices and larger add a serializer/deserializer circuit and PLL for support up to 840 Mbit per channel.

Each bank can support multiple standards with the same VCCIO for output pins. Each bank can support one voltage-referenced I/O standard, but it can support multiple I/O standards with the same VCCIO voltage level. For example, when VCCIO is 3.3 V, a bank can support LVTTTL, LVCMOS, 3.3-V PCI, and SSTL-3 for inputs and outputs.

When the LVDS banks are not used for the LVDS I/O standard, they support all of the other I/O standards. Figure 28 shows the arrangement of the APEX 20KC I/O banks.

Signals can be driven into APEX 20KC devices before and during power-up without damaging the device. In addition, APEX 20KC devices do not drive out during power-up. Once operating conditions are reached and the device is configured, APEX 20KC devices operate as specified by the user.

MultiVolt I/O Interface

The APEX architecture supports the MultiVolt I/O interface feature, which allows APEX devices in all packages to interface with systems of different supply voltages. The devices have one set of VCC pins for internal operation and input buffers (VCCINT), and another set for I/O output drivers (VCCIO).

APEX 20KC devices support the MultiVolt I/O interface feature. The APEX 20KC VCCINT pins must always be connected to a 1.8-V power supply. With a 1.8-V VCCINT level, input pins are 1.8-V, 2.5-V, and 3.3-V tolerant. The VCCIO pins can be connected to either a 1.8-V, 2.5-V, or 3.3-V power supply, depending on the I/O standard requirements. When the VCCIO pins are connected to a 1.8-V power supply, the output levels are compatible with 1.8-V systems. When VCCIO pins are connected to a 2.5-V power supply, the output levels are compatible with 2.5-V systems. When VCCIO pins are connected to a 3.3-V power supply, the output high is 3.3 V and compatible with 3.3-V or 5.0-V systems. An APEX 20KC device is 5.0-V tolerant with the addition of a resistor.

Table 10 summarizes APEX 20KC MultiVolt I/O support.

Table 10. APEX 20KC MultiVolt I/O Support								
V_{CCIO} (V)	Input Signals (V)				Output Signals (V)			
	1.8	2.5	3.3	5.0	1.8	2.5	3.3	5.0
1.8	✓	✓ (1)	✓ (1)		✓			
2.5		✓	✓ (1)			✓		
3.3		✓	✓	✓ (2)		✓ (3)	✓	✓

Notes:

- (1) The PCI clamping diode must be disabled to drive an input with voltages higher than V_{CCIO}, except for the 5.0-V input case.
- (2) An APEX 20KC device can be made 5.0-V tolerant with the addition of an external resistor.
- (3) When V_{CCIO} = 3.3 V, an APEX 20KC device can drive a 2.5-V device with 3.3-V tolerant inputs.

ClockLock & ClockBoost Timing Parameters

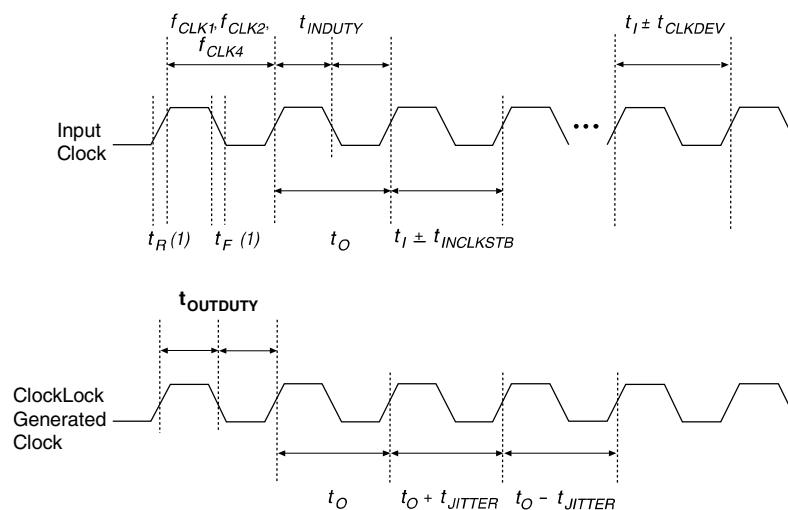
For the ClockLock and ClockBoost circuitry to function properly, the incoming clock must meet certain requirements. If these specifications are not met, the circuitry may not lock onto the incoming clock, which generates an erroneous clock within the device. The clock generated by the ClockLock and ClockBoost circuitry must also meet certain specifications. If the incoming clock meets these requirements during configuration, the APEX 20KC ClockLock and ClockBoost circuitry will lock onto the clock during configuration. The circuit will be ready for use immediately after configuration. In APEX 20KC devices, the clock input standard is programmable, so the PLL cannot respond to the clock until the device is configured. The PLL locks onto the input clock as soon as configuration is complete. Figure 29 shows the incoming and generated clock specifications.



For more information on ClockLock and ClockBoost circuitry, see *Application Note 115: Using the ClockLock and ClockBoost PLL Features in APEX Devices*.

Figure 29. Specifications for the Incoming & Generated Clocks

The t_I parameter refers to the nominal input clock period; the t_O parameter refers to the nominal output clock period.



Note:

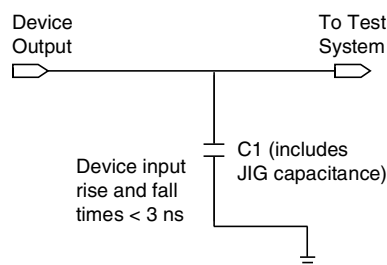
(1) Rise and fall times are measured from 10% to 90%.

Generic Testing

Each APEX 20KC device is functionally tested. Complete testing of each configurable SRAM bit and all logic functionality ensures 100% yield. AC test measurements for APEX 20KC devices are made under conditions equivalent to those shown in Figure 31. Multiple test patterns can be used to configure devices during all stages of the production flow. AC test criteria include:

- Power supply transients can affect AC measurements.
- Simultaneous transitions of multiple outputs should be avoided for accurate measurement.
- Threshold tests must not be performed under AC conditions.
- Large-amplitude, fast-ground-current transients normally occur as the device outputs discharge the load capacitances. When these transients flow through the parasitic inductance between the device ground pin and the test system ground, significant reductions in observable noise immunity can result.

Figure 31. APEX 20KC AC Test Conditions



Operating Conditions

Tables 17 through 20 provide information on absolute maximum ratings, recommended operating conditions, DC operating conditions, and capacitance for 1.8-V APEX 20KC devices.

Table 17. APEX 20KC Device Absolute Maximum Ratings *Note (1)*

Symbol	Parameter	Conditions	Min	Max	Unit
V_{CCINT}	Supply voltage	With respect to ground (2)	-0.5	2.5	V
V_{CCIO}			-0.5	4.6	V
V_I	DC input voltage		-0.5	4.6	V
I_{OUT}	DC output current, per pin		-25	25	mA
T_{STG}	Storage temperature	No bias	-65	150	°C
T_{AMB}	Ambient temperature	Under bias	-65	135	°C
T_J	Junction temperature	PQFP, RQFP, TQFP, and BGA packages, under bias		135	°C
		Ceramic PGA packages, under bias		150	°C

Table 28. GTL+ I/O Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V_{TT}	Termination voltage		1.35	1.5	1.65	V
V_{REF}	Reference voltage		0.88	1.0	1.12	V
V_{IH}	High-level input voltage		$V_{REF} + 0.1$			V
V_{IL}	Low-level input voltage				$V_{REF} - 0.1$	V
V_{OL}	Low-level output voltage	$I_{OL} = 36 \text{ mA}$ (2)			0.65	V

Table 29. SSTL-2 Class I Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V_{CCIO}	I/O supply voltage		2.375	2.5	2.625	V
V_{TT}	Termination voltage		$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$	V
V_{REF}	Reference voltage		1.15	1.25	1.35	V
V_{IH}	High-level input voltage		$V_{REF} + 0.18$		$V_{CCIO} + 0.3$	V
V_{IL}	Low-level input voltage		-0.3		$V_{REF} - 0.18$	V
V_{OH}	High-level output voltage	$I_{OH} = -7.6 \text{ mA}$ (1)	$V_{TT} + 0.57$			V
V_{OL}	Low-level output voltage	$I_{OL} = 7.6 \text{ mA}$ (2)			$V_{TT} - 0.57$	V

Table 30. SSTL-2 Class II Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V_{CCIO}	I/O supply voltage		2.375	2.5	2.625	V
V_{TT}	Termination voltage		$V_{REF} - 0.04$	V_{REF}	$V_{REF} + 0.04$	V
V_{REF}	Reference voltage		1.15	1.25	1.35	V
V_{IH}	High-level input voltage		$V_{REF} + 0.18$		$V_{CCIO} + 0.3$	V
V_{IL}	Low-level input voltage		-0.3		$V_{REF} - 0.18$	V
V_{OH}	High-level output voltage	$I_{OH} = -15.2 \text{ mA}$ (1)	$V_{TT} + 0.76$			V
V_{OL}	Low-level output voltage	$I_{OL} = 15.2 \text{ mA}$ (2)			$V_{TT} - 0.76$	V

Table 31. SSTL-3 Class I Specifications

Symbol	Parameter	Conditions	Minimum	Typical	Maximum	Units
V_{CCIO}	I/O supply voltage		3.0	3.3	3.6	V
V_{TT}	Termination voltage		$V_{REF} - 0.05$	V_{REF}	$V_{REF} + 0.05$	V
V_{REF}	Reference voltage		1.3	1.5	1.7	V
V_{IH}	High-level input voltage		$V_{REF} + 0.2$		$V_{CCIO} + 0.3$	V
V_{IL}	Low-level input voltage		-0.3		$V_{REF} - 0.2$	V
V_{OH}	High-level output voltage	$I_{OH} = -8 \text{ mA}$ (1)	$V_{TT} + 0.6$			V
V_{OL}	Low-level output voltage	$I_{OL} = 8 \text{ mA}$ (2)			$V_{TT} - 0.6$	V

Figure 33 shows the f_{MAX} timing model for APEX 20KC devices.

Figure 33. f_{MAX} Timing Model

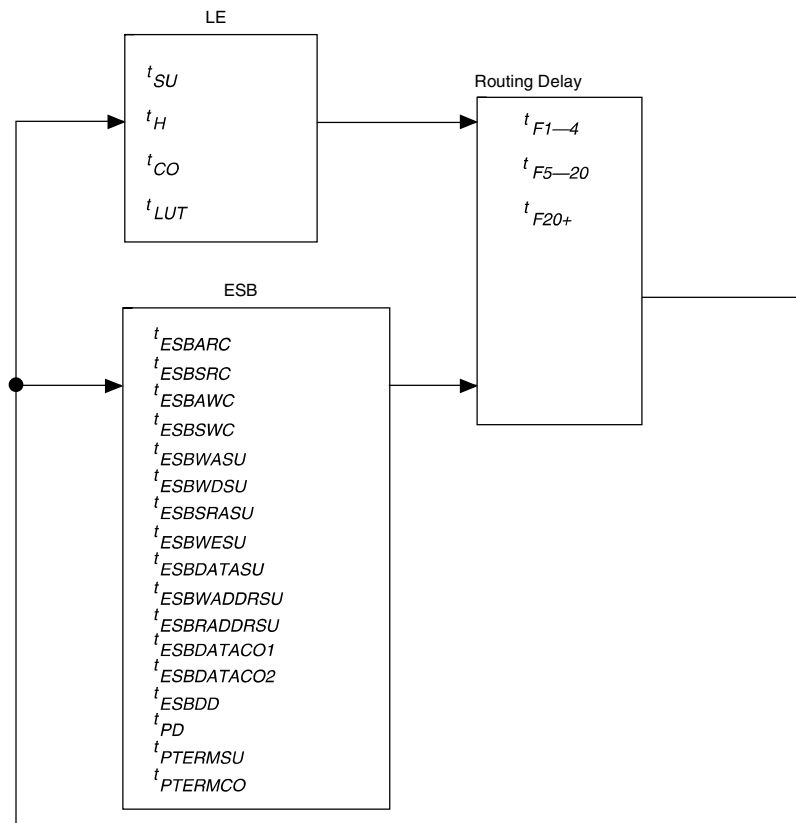


Figure 34 shows the timing model for bidirectional I/O pin timing.

Tables 43 through 78 show the f_{MAX} and external timing parameters for EPC20K100C, EPC20K200C, EP20K400C, EP20K600C, EP20K1000C, and EP20K1500C devices.

Table 43. EP20K100C f_{MAX} LE Timing Parameters *Note (1)*

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t_{SU}	0.3						ns
t_H	0.3						ns
t_{CO}		0.3					ns
t_{LUT}		0.7					ns

Table 44. EP20K100C f_{MAX} ESB Timing Parameters *Note (1)*

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t_{ESBARC}		1.4					ns
t_{ESBSRC}		2.5					ns
t_{ESBAWC}		3.1					ns
t_{ESBSWC}		3.0					ns
$t_{ESBWASU}$	0.5						ns
t_{ESBWAH}	0.5						ns
$t_{ESBWDSU}$	0.6						ns
t_{ESBWDH}	0.5						ns
$t_{ESBRASU}$	1.4						ns
t_{ESBRAH}	0.0						ns
$t_{ESBWESU}$	2.3						ns
$t_{ESBDATASU}$	0.0						ns
$t_{ESBWADDRSU}$	0.2						ns
$t_{ESBRADDRSU}$	0.2						ns
$t_{ESBDATACO1}$		1.0					ns
$t_{ESBDATACO2}$		2.3					ns
t_{ESBDD}		2.7					ns
t_{PD}		1.6					ns
$t_{PTERMSU}$	1.0						ns
$t_{PTERMCO}$		1.0					ns

Table 52. EP20K200C Minimum Pulse Width Timing Parameters *Note (1)*

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t_{CH}	2.2						ns
t_{CL}	2.3						ns
t_{CLRP}	0.2						ns
t_{PREP}	0.2						ns
t_{ESBCH}	2.3						ns
t_{ESBCL}	2.3						ns
t_{ESBWP}	1.1						ns
t_{ESBRP}	0.9						ns

Table 53. EP20K200C External Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade (2)		-9 Speed Grade (2)		Unit
	Min	Max	Min	Max	Min	Max	
t_{INSU}	2.0						ns
t_{INH}	0.0						ns
t_{OUTCO}	2.0	5.0					ns
$t_{INSUPLL}$	3.3						ns
t_{INHPLL}	0.0						ns
$t_{OUTCOPLL}$	0.5	2.1					ns

Table 78. EP20K1500C External Bidirectional Timing Parameters

Symbol	-7 Speed Grade		-8 Speed Grade ⁽²⁾		-9 Speed Grade ⁽²⁾		Unit
	Min	Max	Min	Max	Min	Max	
t _{INSUBIDIR}	2.6						ns
t _{INHBIDIR}	0.0						ns
t _{OUTCOBIDIR}	2.0	5.0					ns
t _{XZBIDIR}		7.1					ns
t _{ZXBIDIR}		7.1					ns
t _{INSUBIDIRPLL}	3.9						ns
t _{INHBIDIRPLL}	0.0						ns
t _{OUTCOBIDIRPLL}	0.5	2.1					ns
t _{XZBIDIRPLL}		4.2					ns
t _{ZXBIDIRPLL}		4.2					ns

Notes to tables:

- (1) Timing information is preliminary. Final timing information will be released in a future version of this data sheet.
 (2) Timing information for these devices will be released in a future version of this data sheet.

Tables 79 and 80 show selectable I/O standard input and output delays for APEX 20KC devices. If you select an I/O standard input or output delay other than LVCMOS, add the delay for the selected speed grade to the LVCMOS value.

Table 79. Selectable I/O Standard Input Delays

Symbol	-7 Speed Grade		-8 Speed Grade ⁽¹⁾		-9 Speed Grade ⁽¹⁾		Unit
	Min	Max	Min	Max	Min	Max	Min
LVC MOS		0.0					ns
LVTTL		0.0					ns
2.5 V		0.1					ns
1.8 V		0.5					ns
PCI		0.4					ns
GTL+		−0.3					ns
SSTL-3 Class I		−0.4					ns
SSTL-3 Class II		−0.4					ns
SSTL-2 Class I		−0.3					ns
SSTL-2 Class II		−0.3					ns
LVDS		−0.2					ns
CTT		−0.3					ns
AGP		0.0					ns

Table 80. Selectable I/O Standard Output Delays

Symbol	-7 Speed Grade		-8 Speed Grade ⁽¹⁾		-9 Speed Grade ⁽¹⁾		Unit
	Min	Max	Min	Max	Min	Max	Min
LVC MOS		0.0					ns
LVTTL		0.0					ns
2.5 V		0.5					ns
1.8 V		1.7					ns
PCI		−0.2					ns
GTL+		−0.4					ns
SSTL-3 Class I		−0.1					ns
SSTL-3 Class II		−0.6					ns
SSTL-2 Class I		0.0					ns
SSTL-2 Class II		−0.4					ns
LVDS		−0.8					ns
CTT		−0.2					ns
AGP		−0.4					ns

Note to tables:

(1) Timing information will be released in a future version of this data sheet.

Multiple APEX 20KC devices can be configured in any of five configuration schemes by connecting the configuration enable (nCE) and configuration enable output (nCEO) pins on each device.

Table 81. Data Sources for Configuration

Configuration Scheme	Data Source
Configuration device	EPC16, EPC2, or EPC1 configuration device
Passive serial (PS)	MasterBlaster or ByteBlasterMV download cable or serial data source
Passive parallel asynchronous (PPA)	Parallel data source
Passive parallel synchronous (PPS)	Parallel data source
JTAG	MasterBlaster or ByteBlasterMV download cable or a microprocessor with a Jam Standard Test and Programming Language (STAPL) or JBC File



For more information on configuration, see *Application Note 116 (Configuring APEX 20K, FLEX 10K & FLEX 6000 Devices.)*

Device Pin-Outs

See the Altera web site (<http://www.altera.com>) or the *Altera Digital Library* for pin-out information.

Revision History

The information contained in the *APEX 20KC Programmable Logic Device Data Sheet* version 1.1 supersedes information published in previous versions.

The following changes were made to the *APEX 20KC Programmable Logic Device Data Sheet* version 1.1: updated maximum user I/O pins in [Table 1](#).